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Details

Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPS
Connectivity	I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	25
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 8x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	36-VFTLA Exposed Pad
Supplier Device Package	36-VTLA (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep64mc203-i-tl

FIGURE 2-5: SINGLE-PHASE SYNCHRONOUS BUCK CONVERTER

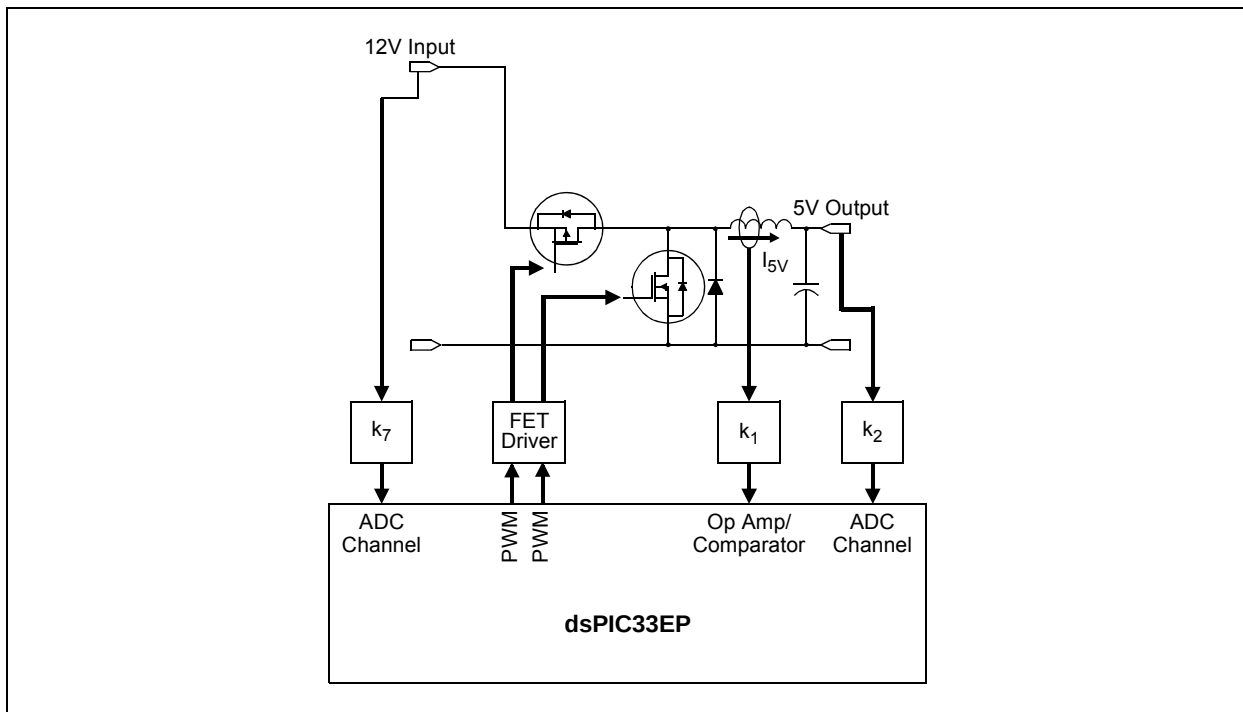


FIGURE 2-6: MULTIPHASE SYNCHRONOUS BUCK CONVERTER

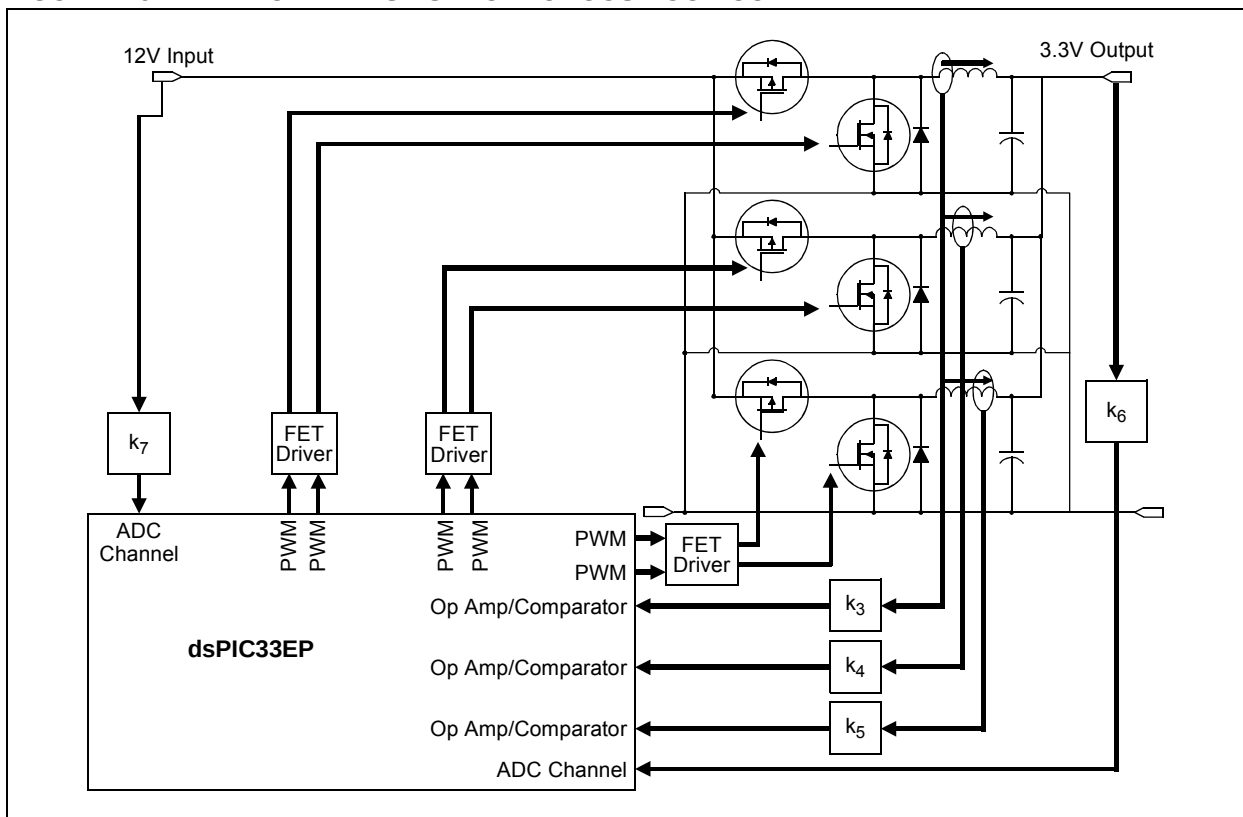


TABLE 4-4: INTERRUPT CONTROLLER REGISTER MAP FOR PIC24EPXXXMC20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IFS0	0800	—	DMA1IF	AD1IF	U1TXIF	U1RXIF	SPI1IF	SPI1EIF	T3IF	T2IF	OC2IF	IC2IF	DMA0IF	T1IF	OC1IF	IC1IF	INT0IF	0000
IFS1	0802	U2TXIF	U2RXIF	INT2IF	T5IF	T4IF	OC4IF	OC3IF	DMA2IF	—	—	—	INT1IF	CNIF	CMIF	MI2C1IF	SI2C1IF	0000
IFS2	0804	—	—	—	—	—	—	—	—	—	IC4IF	IC3IF	DMA3IF	—	—	SPI2IF	SPI2EIF	0000
IFS3	0806	—	—	—	—	—	QE11IF	PSEMIF	—	—	—	—	—	—	MI2C2IF	SI2C2IF	—	0000
IFS4	0808	—	—	CTMUIF	—	—	—	—	—	—	—	—	—	CRCIF	U2EIF	U1EIF	—	0000
IFS5	080A	PWM2IF	PWM1IF	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IFS6	080C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	PWM3IF	0000
IFS8	0810	JTAGIF	ICDIF	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IFS9	0812	—	—	—	—	—	—	—	—	—	PTG3IF	PTG2IF	PTG1IF	PTG0IF	PTGWDTIF	PTGSTEIF	—	0000
IEC0	0820	—	DMA1IE	AD1IE	U1TXIE	U1RXIE	SPI1IE	SPI1EIE	T3IE	T2IE	OC2IE	IC2IE	DMA0IE	T1IE	OC1IE	IC1IE	INT0IE	0000
IEC1	0822	U2TXIE	U2RXIE	INT2IE	T5IE	T4IE	OC4IE	OC3IE	DMA2IE	—	—	—	INT1IE	CNIE	CMIE	MI2C1IE	SI2C1IE	0000
IEC2	0824	—	—	—	—	—	—	—	—	—	IC4IE	IC3IE	DMA3IE	—	—	SPI2IE	SPI2EIE	0000
IEC3	0826	—	—	—	—	—	QE11IE	PSEMIE	—	—	—	—	—	—	MI2C2IE	SI2C2IE	—	0000
IEC4	0828	—	—	CTMUIE	—	—	—	—	—	—	—	—	—	—	CRCIE	U2EIE	U1EIE	0000
IEC5	082A	PWM2IE	PWM1IE	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IEC6	082C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	PWM3IE	0000
IEC8	0830	JTAGIE	ICDIE	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IEC9	0832	—	—	—	—	—	—	—	—	—	PTG3IE	PTG2IE	PTG1IE	PTG0IE	PTGWDTIE	PTGSTIEIE	—	0000
IPC0	0840	—	T1IP<2:0>			—	OC1IP<2:0>			—	IC1IP<2:0>			—	INT0IP<2:0>			4444
IPC1	0842	—	T2IP<2:0>			—	OC2IP<2:0>			—	IC2IP<2:0>			—	DMA0IP<2:0>			4444
IPC2	0844	—	U1RXIP<2:0>			—	SPI1IP<2:0>			—	SPI1EIP<2:0>			—	T3IP<2:0>			4444
IPC3	0846	—	—	—	—	—	DMA1IP<2:0>			—	AD1IP<2:0>			—	U1TXIP<2:0>			0444
IPC4	0848	—	CNIP<2:0>			—	CMIP<2:0>			—	MI2C1IP<2:0>			—	SI2C1IP<2:0>			4444
IPC5	084A	—	—	—	—	—	—	—	—	—	—	—	—	—	INT1IP<2:0>			0004
IPC6	084C	—	T4IP<2:0>			—	OC4IP<2:0>			—	OC3IP<2:0>			—	DMA2IP<2:0>			4444
IPC7	084E	—	U2TXIP<2:0>			—	U2RXIP<2:0>			—	INT2IP<2:0>			—	T5IP<2:0>			4444
IPC8	0850	—	—	—	—	—	—	—	—	—	SPI2IP<2:0>			—	SPI2EIP<2:0>			0044
IPC9	0852	—	—	—	—	—	IC4IP<2:0>			—	IC3IP<2:0>			—	DMA3IP<2:0>			0444
IPC12	0858	—	—	—	—	—	MI2C2IP<2:0>			—	SI2C2IP<2:0>			—	—	—	—	0440
IPC14	085C	—	—	—	—	—	QE11IP<2:0>			—	PSEMIP<2:0>			—	—	—	—	0440
IPC16	0860	—	CRCIP<2:0>			—	U2EIP<2:0>			—	U1EIP<2:0>			—	—	—	—	4440
IPC19	0866	—	—	—	—	—	—	—	—	—	CTMUIP<2:0>			—	—	—	—	0040
IPC23	086E	—	PWM2IP<2:0>			—	PWM1IP<2:0>			—	—	—	—	—	—	—	—	4400
IPC24	0870	—	—	—	—	—	—	—	—	—	—	—	—	—	PWM3IP<2:0>			4004

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-7: INTERRUPT CONTROLLER REGISTER MAP FOR dsPIC33EPXXXMC50X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IFS0	0800	—	DMA1IF	AD1IF	U1TXIF	U1RXIF	SPI1IF	SPI1EIF	T3IF	T2IF	OC2IF	IC2IF	DMA0IF	T1IF	OC1IF	IC1IF	INT0IF	0000
IFS1	0802	U2TXIF	U2RXIF	INT2IF	T5IF	T4IF	OC4IF	OC3IF	DMA2IF	—	—	—	INT1IF	CNIF	CMIF	M12C1IF	SI2C1IF	0000
IFS2	0804	—	—	—	—	—	—	—	—	—	IC4IF	IC3IF	DMA3IF	C1IF	C1RXIF	SPI2IF	SPI2EIF	0000
IFS3	0806	—	—	—	—	—	QE11IF	PSEMIF	—	—	—	—	—	—	M12C2IF	SI2C2IF	—	0000
IFS4	0808	—	—	CTMUIF	—	—	—	—	—	—	C1TXIF	—	—	CRCIF	U2EIF	U1EIF	—	0000
IFS5	080A	PWM2IF	PWM1IF	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IFS6	080C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	PWM3IF	0000
IFS8	0810	JTAGIF	ICDIF	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IFS9	0812	—	—	—	—	—	—	—	—	—	PTG3IF	PTG2IF	PTG1IF	PTG0IF	PTGWDTIF	PTGSTIEIF	—	0000
IEC0	0820	—	DMA1IE	AD1IE	U1TXIE	U1RXIE	SPI1IE	SPI1EIE	T3IE	T2IE	OC2IE	IC2IE	DMA0IE	T1IE	OC1IE	IC1IE	INT0IE	0000
IEC1	0822	U2TXIE	U2RXIE	INT2IE	T5IE	T4IE	OC4IE	OC3IE	DMA2IE	—	—	—	INT1IE	CNIE	CMIE	M12C1IE	SI2C1IE	0000
IEC2	0824	—	—	—	—	—	—	—	—	—	IC4IE	IC3IE	DMA3IE	C1IE	C1RXIE	SPI2IE	SPI2EIE	0000
IEC3	0826	—	—	—	—	—	QE11IE	PSEMIE	—	—	—	—	—	—	M12C2IE	SI2C2IE	—	0000
IEC4	0828	—	—	CTMUIE	—	—	—	—	—	—	C1TXIE	—	—	CRCIE	U2EIE	U1EIE	—	0000
IEC5	082A	PWM2IE	PWM1IE	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IEC6	082C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	PWM3IE	0000
IEC7	082E	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IEC8	0830	JTAGIE	ICDIE	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IEC9	0832	—	—	—	—	—	—	—	—	—	PTG3IE	PTG2IE	PTG1IE	PTG0IE	PTGWDTIE	PTGSTIEIE	—	0000
IPC0	0840	—	T1IP<2:0>			—	OC1IP<2:0>			—	IC1IP<2:0>			—	INT0IP<2:0>			4444
IPC1	0842	—	T2IP<2:0>			—	OC2IP<2:0>			—	IC2IP<2:0>			—	DMA0IP<2:0>			4444
IPC2	0844	—	U1RXIP<2:0>			—	SPI1IP<2:0>			—	SPI1EIP<2:0>			—	T3IP<2:0>			4444
IPC3	0846	—	—	—	—	—	DMA1IP<2:0>			—	AD1IP<2:0>			—	U1TXIP<2:0>			0444
IPC4	0848	—	CNIP<2:0>			—	CMIP<2:0>			—	M12C1IP<2:0>			—	SI2C1IP<2:0>			4444
IPC5	084A	—	—	—	—	—	—	—	—	—	—	—	—	—	INT1IP<2:0>			0004
IPC6	084C	—	T4IP<2:0>			—	OC4IP<2:0>			—	OC3IP<2:0>			—	DMA2IP<2:0>			4444
IPC7	084E	—	U2TXIP<2:0>			—	U2RXIP<2:0>			—	INT2IP<2:0>			—	T5IP<2:0>			4444
IPC8	0850	—	C1IP<2:0>			—	C1RXIP<2:0>			—	SPI2IP<2:0>			—	SPI2EIP<2:0>			4444
IPC9	0852	—	—	—	—	—	IC4IP<2:0>			—	IC3IP<2:0>			—	DMA3IP<2:0>			0444
IPC12	0858	—	—	—	—	—	M12C2IP<2:0>			—	SI2C2IP<2:0>			—	—	—	—	0440
IPC14	085C	—	—	—	—	—	QE11IP<2:0>			—	PSEMIP<2:0>			—	—	—	—	0440
IPC16	0860	—	CRCIP<2:0>			—	U2EIP<2:0>			—	U1EIP<2:0>			—	—	—	—	4440
IPC17	0862	—	—	—	—	—	C1TXIP<2:0>			—	—	—	—	—	—	—	—	0400
IPC19	0866	—	—	—	—	—	—	—	—	—	CTMUIP<2:0>			—	—	—	—	0040

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-7: INTERRUPT CONTROLLER REGISTER MAP FOR dsPIC33EPXXXMC50X DEVICES ONLY (CONTINUED)

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IPC23	086E	—	PWM2IP<2:0>			—	PWM1IP<2:0>			—	—	—	—	—	—	—	—	4400
IPC24	0870	—	—	—	—	—	—	—	—	—	—	—	—	—	PWM3IP<2:0>			0004
IPC35	0886	—	JTAGIP<2:0>			—	ICDIP<2:0>			—	—	—	—	—	—	—	—	4400
IPC36	0888	—	PTG0IP<2:0>			—	PTGWDTIP<2:0>			—	PTGSTEPIP<2:0>			—	—	—	—	4440
IPC37	088A	—	—	—	—	—	PTG3IP<2:0>			—	PTG2IP<2:0>			—	PTG1IP<2:0>			0444
INTCON1	08C0	NSTDIS	OVAERR	OVBERR	COVAERR	COVBERR	OVATE	OVATE	OVATE	SFTACERR	DIV0ERR	DMACERR	MATHERR	ADDRERR	STKERR	OSCFail	—	0000
INTCON2	08C2	GIE	DISI	SWTRAP	—	—	—	—	—	—	—	—	—	—	INT2EP	INT1EP	INT0EP	8000
INTCON3	08C4	—	—	—	—	—	—	—	—	—	—	DAE	DOOVR	—	—	—	—	0000
INTCON4	08C6	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SGHT	0000
INTTREG	08C8	—	—	—	—	ILR<3:0>				VECNUM<7:0>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

6.0 RESETS

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “Reset” (DS70602) in the “dsPIC33/PIC24 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The Reset module combines all Reset sources and controls the device Master Reset Signal, $\overline{\text{SYSRST}}$. The following is a list of device Reset sources:

- POR: Power-on Reset
- BOR: Brown-out Reset
- $\overline{\text{MCLR}}$: Master Clear Pin Reset
- SWR: RESET Instruction
- WDTO: Watchdog Timer Time-out Reset
- CM: Configuration Mismatch Reset
- TRAPR: Trap Conflict Reset
- IOPUWR: Illegal Condition Device Reset
 - Illegal Opcode Reset
 - Uninitialized W Register Reset
 - Security Reset

A simplified block diagram of the Reset module is shown in Figure 6-1.

Any active source of Reset will make the $\overline{\text{SYSRST}}$ signal active. On system Reset, some of the registers associated with the CPU and peripherals are forced to a known Reset state and some are unaffected.

Note: Refer to the specific peripheral section or **Section 4.0 “Memory Organization”** of this manual for register Reset states.

All types of device Reset set a corresponding status bit in the RCON register to indicate the type of Reset (see Register 6-1).

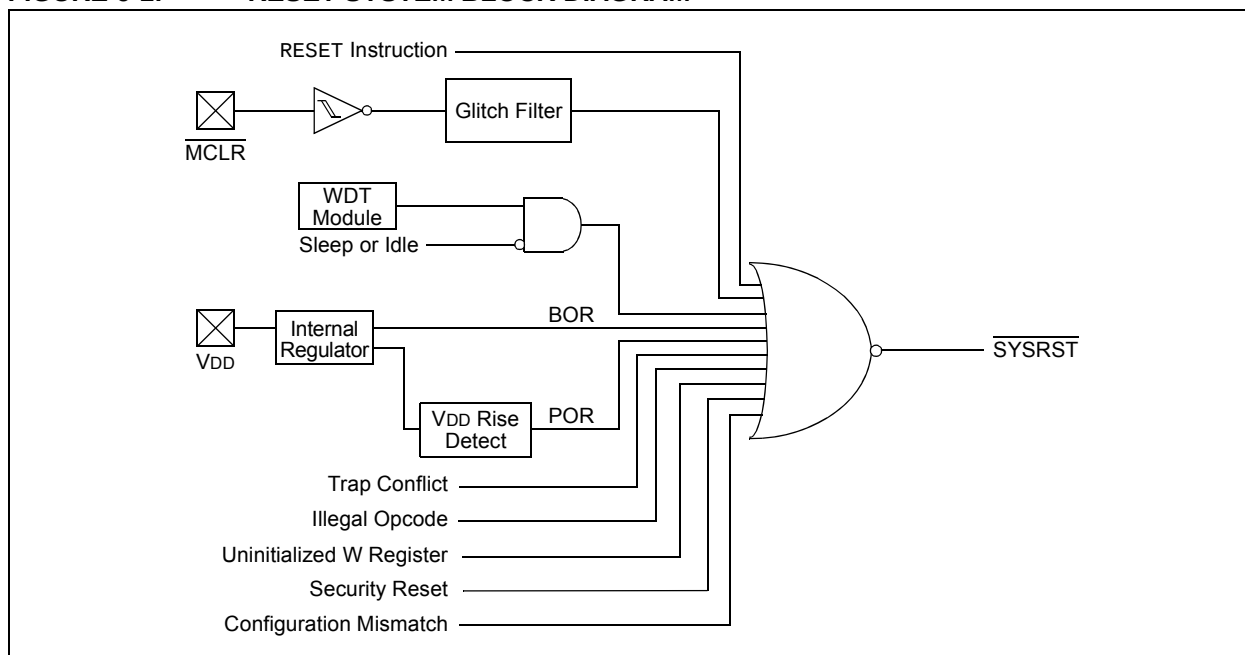
A POR clears all the bits, except for the POR and BOR bits ($\text{RCON}<1:0>$), that are set. The user application can set or clear any bit at any time during code execution. The RCON bits only serve as status bits. Setting a particular Reset status bit in software does not cause a device Reset to occur.

The RCON register also has other bits associated with the Watchdog Timer and device power-saving states. The function of these bits is discussed in other sections of this manual.

Note: The status bits in the RCON register should be cleared after they are read so that the next RCON register value after a device Reset is meaningful.

For all Resets, the default clock source is determined by the $\text{FNOSC}<2:0>$ bits in the FOSCSEL Configuration register. The value of the $\text{FNOSC}<2:0>$ bits is loaded into $\text{NOSC}<2:0>$ ($\text{OSCCON}<10:8>$) on Reset, which in turn, initializes the system clock.

FIGURE 6-1: RESET SYSTEM BLOCK DIAGRAM



REGISTER 7-7: INTTREG: INTERRUPT CONTROL AND STATUS REGISTER

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	ILR3	ILR2	ILR1	ILR0
bit 15				bit 8			

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
VECNUM7	VECNUM6	VECNUM5	VECNUM4	VECNUM3	VECNUM2	VECNUM1	VECNUM0
bit 7				bit 0			

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'

bit 11-8 **ILR<3:0>:** New CPU Interrupt Priority Level bits
1111 = CPU Interrupt Priority Level is 15
•
•
•
0001 = CPU Interrupt Priority Level is 1
0000 = CPU Interrupt Priority Level is 0

bit 7-0 **VECNUM<7:0>:** Vector Number of Pending Interrupt bits
11111111 = 255, Reserved; do not use
•
•
•
00001001 = 9, IC1 – Input Capture 1
00001000 = 8, INT0 – External Interrupt 0
00000111 = 7, Reserved; do not use
00000110 = 6, Generic soft error trap
00000101 = 5, DMAC error trap
00000100 = 4, Math error trap
00000011 = 3, Stack error trap
00000010 = 2, Generic hard trap
00000001 = 1, Address error trap
00000000 = 0, Oscillator fail trap

REGISTER 17-17: INT1TMRH: INTERVAL 1 TIMER HIGH WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTTMR<31:24>							
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTTMR<23:16>							
bit 7				bit 0			

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-0 **INTTMR<31:16>**: High Word Used to Form 32-Bit Interval Timer Register (INT1TMR) bits

REGISTER 17-18: INT1TMRL: INTERVAL 1 TIMER LOW WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTTMR<15:8>							
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTTMR<7:0>							
bit 7				bit 0			

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-0 **INTTMR<15:0>**: Low Word Used to Form 32-Bit Interval Timer Register (INT1TMR) bits

REGISTER 17-19: INT1HLDH: INTERVAL 1 TIMER HOLD HIGH WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTHLD<31:24>							
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTHLD<23:16>							
bit 7				bit 0			

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-0 **INTHLD<31:16>**: Hold Register for Reading and Writing INT1TMRH bits

REGISTER 17-20: INT1HLDL: INTERVAL 1 TIMER HOLD LOW WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTHLD<15:8>							
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTHLD<7:0>							
bit 7				bit 0			

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-0 **INTHLD<15:0>**: Hold Register for Reading and Writing INT1TMRL bits

REGISTER 21-2: CxCTRL2: ECANx CONTROL REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
—	—	—	DNCNT4	DNCNT3	DNCNT2	DNCNT1	DNCNT0
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-5 **Unimplemented:** Read as '0'bit 4-0 **DNCNT<4:0>:** DeviceNet™ Filter Bit Number bits

10010 - 11111 = Invalid selection

10001 = Compares up to Data Byte 3, bit 6 with EID<17>

•

•

•

00001 = Compares up to Data Byte 1, bit 7 with EID<0>

00000 = Does not compare data bytes

REGISTER 21-6: CxINTF: ECANx INTERRUPT FLAG REGISTER

U-0	U-0	R-0	R-0	R-0	R-0	R-0	R-0
—	—	TXBO	TXBP	RXBP	TXWAR	RXWAR	EWARN
bit 15							
							bit 8

R/C-0	R/C-0	R/C-0	U-0	R/C-0	R/C-0	R/C-0	R/C-0
IVRIF	WAKIF	ERRIF	—	FIFOIF	RBOVIF	RBIF	TBIF
bit 7							
							bit 0

Legend:	C = Writable bit, but only '0' can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14	Unimplemented: Read as '0'
bit 13	TXBO: Transmitter in Error State Bus Off bit 1 = Transmitter is in Bus Off state 0 = Transmitter is not in Bus Off state
bit 12	TXBP: Transmitter in Error State Bus Passive bit 1 = Transmitter is in Bus Passive state 0 = Transmitter is not in Bus Passive state
bit 11	RXBP: Receiver in Error State Bus Passive bit 1 = Receiver is in Bus Passive state 0 = Receiver is not in Bus Passive state
bit 10	TXWAR: Transmitter in Error State Warning bit 1 = Transmitter is in Error Warning state 0 = Transmitter is not in Error Warning state
bit 9	RXWAR: Receiver in Error State Warning bit 1 = Receiver is in Error Warning state 0 = Receiver is not in Error Warning state
bit 8	EWARN: Transmitter or Receiver in Error State Warning bit 1 = Transmitter or receiver is in Error Warning state 0 = Transmitter or receiver is not in Error Warning state
bit 7	IVRIF: Invalid Message Interrupt Flag bit 1 = Interrupt request has occurred 0 = Interrupt request has not occurred
bit 6	WAKIF: Bus Wake-up Activity Interrupt Flag bit 1 = Interrupt request has occurred 0 = Interrupt request has not occurred
bit 5	ERRIF: Error Interrupt Flag bit (multiple sources in CxINTF<13:8>) 1 = Interrupt request has occurred 0 = Interrupt request has not occurred
bit 4	Unimplemented: Read as '0'
bit 3	FIFOIF: FIFO Almost Full Interrupt Flag bit 1 = Interrupt request has occurred 0 = Interrupt request has not occurred
bit 2	RBOVIF: RX Buffer Overflow Interrupt Flag bit 1 = Interrupt request has occurred 0 = Interrupt request has not occurred

25.3 Op Amp/Comparator Registers

REGISTER 25-1: CMSTAT: OP AMP/COMPARATOR STATUS REGISTER

R/W-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
PSIDL	—	—	—	C4EVT ⁽¹⁾	C3EVT ⁽¹⁾	C2EVT ⁽¹⁾	C1EVT ⁽¹⁾
bit 15				bit 8			

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	C4OUT ⁽²⁾	C3OUT ⁽²⁾	C2OUT ⁽²⁾	C1OUT ⁽²⁾
bit 7				bit 0			

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

- bit 15 **PSIDL:** Comparator Stop in Idle Mode bit
 1 = Discontinues operation of all comparators when device enters Idle mode
 0 = Continues operation of all comparators in Idle mode
- bit 14-12 **Unimplemented:** Read as '0'
- bit 11 **C4EVT:** Op Amp/Comparator 4 Event Status bit⁽¹⁾
 1 = Op amp/comparator event occurred
 0 = Op amp/comparator event did not occur
- bit 10 **C3EVT:** Comparator 3 Event Status bit⁽¹⁾
 1 = Comparator event occurred
 0 = Comparator event did not occur
- bit 9 **C2EVT:** Comparator 2 Event Status bit⁽¹⁾
 1 = Comparator event occurred
 0 = Comparator event did not occur
- bit 8 **C1EVT:** Comparator 1 Event Status bit⁽¹⁾
 1 = Comparator event occurred
 0 = Comparator event did not occur
- bit 7-4 **Unimplemented:** Read as '0'
- bit 3 **C4OUT:** Comparator 4 Output Status bit⁽²⁾
When CPOL = 0:
 1 = VIN+ > VIN-
 0 = VIN+ < VIN-
When CPOL = 1:
 1 = VIN+ < VIN-
 0 = VIN+ > VIN-
- bit 2 **C3OUT:** Comparator 3 Output Status bit⁽²⁾
When CPOL = 0:
 1 = VIN+ > VIN-
 0 = VIN+ < VIN-
When CPOL = 1:
 1 = VIN+ < VIN-
 0 = VIN+ > VIN-

- Note 1:** Reflects the value of the CEVT bit in the respective Op Amp/Comparator Control register, CMxCON<9>.
- 2:** Reflects the value of the COUT bit in the respective Op Amp/Comparator Control register, CMxCON<8>.

FIGURE 30-13: QEI MODULE INDEX PULSE TIMING CHARACTERISTICS
(dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

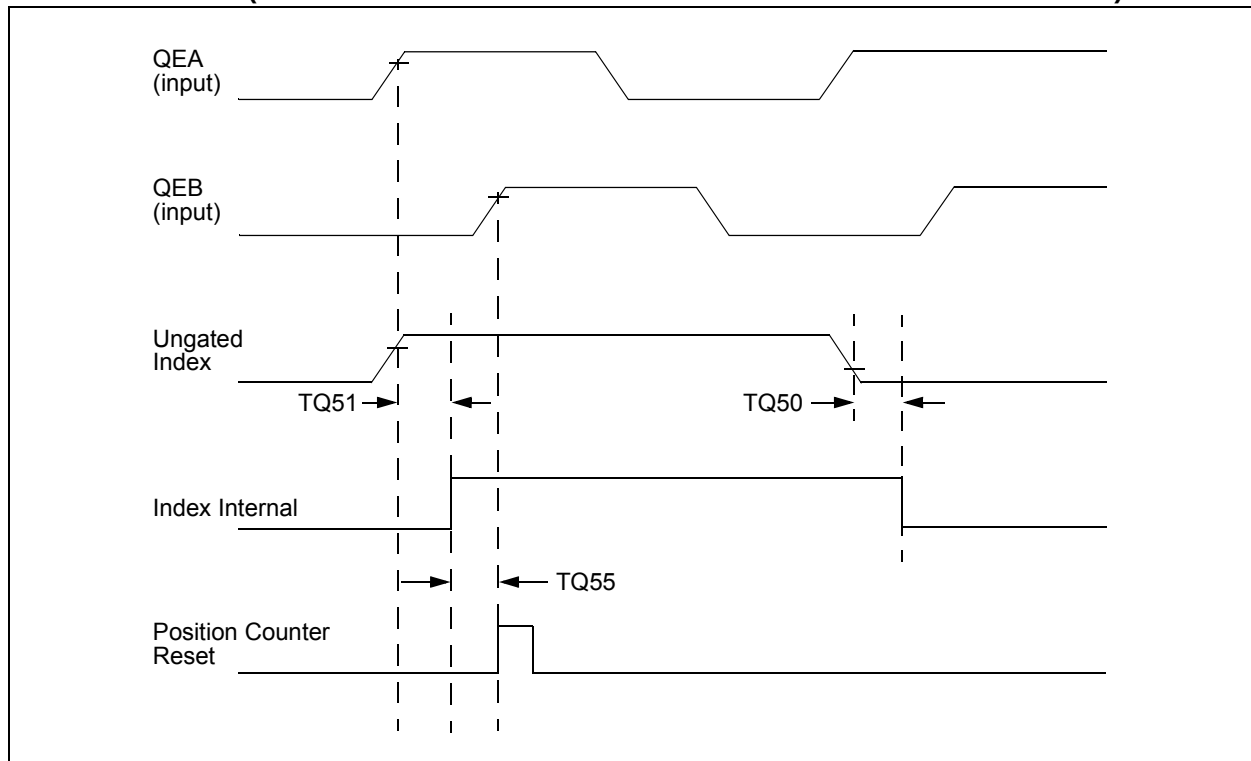


TABLE 30-32: QEI INDEX PULSE TIMING REQUIREMENTS
(dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended			
Param No.	Symbol	Characteristic ⁽¹⁾	Min.	Max.	Units	Conditions
TQ50	TqiL	Filter Time to Recognize Low, with Digital Filter	$3 * N * T_{CY}$	—	ns	$N = 1, 2, 4, 16, 32, 64, 128$ and 256 (Note 2)
TQ51	TqiH	Filter Time to Recognize High, with Digital Filter	$3 * N * T_{CY}$	—	ns	$N = 1, 2, 4, 16, 32, 64, 128$ and 256 (Note 2)
TQ55	Tqidxr	Index Pulse Recognized to Position Counter Reset (ungated index)	$3 T_{CY}$	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Alignment of index pulses to QEA and QEB is shown for position counter Reset timing only. Shown for forward direction only (QEA leads QEB). Same timing applies for reverse direction (QEA lags QEB) but index pulse recognition occurs on the falling edge.

**TABLE 30-37: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0)
TIMING REQUIREMENTS**

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	Symbol	Characteristic ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Units	Conditions
SP70	FscP	Maximum SCK2 Input Frequency	—	—	Lesser of Fp or 15	MHz	(Note 3)
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP35	Tsch2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	Tsch2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS2}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS2}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	(Note 4)
SP52	Tsch2ssH TscL2ssH	$\overline{SS2}$ ↑ after SCK2 Edge	1.5 Tcy + 40	—	—	ns	(Note 4)
SP60	TssL2doV	SDO2 Data Output Valid after $\overline{SS2}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-53: OP AMP/COMPARATOR SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) ⁽¹⁾ Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ. ⁽²⁾	Max.	Units	Conditions
Op Amp DC Characteristics							
CM40	VCMR	Common-Mode Input Voltage Range	AVSS	—	AVDD	V	
CM41	CMRR	Common-Mode Rejection Ratio ⁽³⁾	—	40	—	db	VCM = AVDD/2
CM42	VOFFSET	Op Amp Offset Voltage ⁽³⁾	—	±5	—	mV	
CM43	VGAIN	Open-Loop Voltage Gain ⁽³⁾	—	90	—	db	
CM44	IOS	Input Offset Current	—	—	—	—	See pad leakage currents in Table 30-11
CM45	IB	Input Bias Current	—	—	—	—	See pad leakage currents in Table 30-11
CM46	IOUT	Output Current	—	—	420	μA	With minimum value of RFEEDBACK (CM48)
CM48	RFEEDBACK	Feedback Resistance Value	8	—	—	kΩ	
CM49a	VOADC	Output Voltage Measured at OAx Using ADC ^(3,4)	AVSS + 0.077 AVSS + 0.037 AVSS + 0.018	— — —	AVDD – 0.077 AVDD – 0.037 AVDD – 0.018	V V V	IOUT = 420 μA IOUT = 200 μA IOUT = 100 μA
CM49b	VOUT	Output Voltage Measured at OAxOUT Pin ^(3,4,5)	AVSS + 0.210 AVSS + 0.100 AVSS + 0.050	— — —	AVDD – 0.210 AVDD – 0.100 AVDD – 0.050	V V V	IOUT = 420 μA IOUT = 200 μA IOUT = 100 μA
CM51	RINT1 ⁽⁶⁾	Internal Resistance 1 (Configuration A and B) ^(3,4,5)	198	264	317	Ω	Min = -40°C Typ = +25°C Max = +125°C

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

3: Parameter is characterized but not tested in manufacturing.

4: See Figure 25-6 for configuration information.

5: See Figure 25-7 for configuration information.

6: Resistances can vary by ±10% between op amps.

TABLE 30-57: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) ⁽¹⁾ Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of: VDD – 0.3 or 3.0	—	Lesser of: VDD + 0.3 or 3.6	V	
AD02	AVSS	Module Vss Supply	Vss – 0.3	—	Vss + 0.3	V	
Reference Inputs							
AD05	VREFH	Reference Voltage High	AVss + 2.5	—	AVDD	V	VREFH = VREF+ VREFL = VREF- (Note 1)
AD05a			3.0	—	3.6	V	VREFH = AVDD VREFL = AVSS = 0
AD06	VREFL	Reference Voltage Low	AVSS	—	AVDD – 2.5	V	(Note 1)
AD06a			0	—	0	V	VREFH = AVDD VREFL = AVSS = 0
AD07	VREF	Absolute Reference Voltage	2.5	—	3.6	V	VREF = VREFH - VREFL
AD08	IREF	Current Drain	— —	— —	10 600	μA μA	ADC off ADC on
AD09	IAD	Operating Current ⁽²⁾	—	5	—	mA	ADC operating in 10-bit mode (Note 1)
			—	2	—	mA	ADC operating in 12-bit mode (Note 1)
Analog Input							
AD12	VINH	Input Voltage Range VINH	VINL	—	VREFH	V	This voltage reflects Sample-and-Hold Channels 0, 1, 2 and 3 (CH0-CH3), positive input
AD13	VINL	Input Voltage Range VINL	VREFL	—	AVSS + 1V	V	This voltage reflects Sample-and-Hold Channels 0, 1, 2 and 3 (CH0-CH3), negative input
AD17	RIN	Recommended Impedance of Analog Voltage Source	—	—	200	Ω	Impedance to achieve maximum performance of ADC

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Parameter is characterized but not tested in manufacturing.

TABLE 30-61: ADC CONVERSION (10-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) ⁽¹⁾ Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
Clock Parameters							
AD50	TAD	ADC Clock Period	76	—	—	ns	
AD51	tRC	ADC Internal RC Oscillator Period ⁽²⁾	—	250	—	ns	
Conversion Rate							
AD55	tCONV	Conversion Time	—	12 TAD	—	—	
AD56	FCNV	Throughput Rate	—	—	1.1	Msp/s	Using simultaneous sampling
AD57a	TSAMP	Sample Time when Sampling any ANx Input	2 TAD	—	—	—	
AD57b	TSAMP	Sample Time when Sampling the Op Amp Outputs (Configuration A and Configuration B) ^(4,5)	4 TAD	—	—	—	
Timing Parameters							
AD60	tPCS	Conversion Start from Sample Trigger ^(2,3)	2 TAD	—	3 TAD	—	Auto-convert trigger is not selected
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit ^(2,3)	2 TAD	—	3 TAD	—	
AD62	tCSS	Conversion Completion to Sample Start (ASAM = 1) ^(2,3)	—	0.5 TAD	—	—	
AD63	tDPU	Time to Stabilize Analog Stage from ADC Off to ADC On ^(2,3)	—	—	20	μs	(Note 6)

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Parameters are characterized but not tested in manufacturing.

3: Because the sample caps will eventually lose charge, clock rates below 10 kHz may affect linearity performance, especially at elevated temperatures.

4: See Figure 25-6 for configuration information.

5: See Figure 25-7 for configuration information.

6: The parameter, tDPU, is the time required for the ADC module to stabilize at the appropriate level when the module is turned on (ADON (AD1CON1<15>) = 1). During this time, the ADC result is indeterminate.

TABLE 30-62: DMA MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Characteristic	Min.	Typ. ⁽¹⁾	Max.	Units	Conditions
DM1	DMA Byte/Word Transfer Latency	1 Tcy ⁽²⁾	—	—	ns	

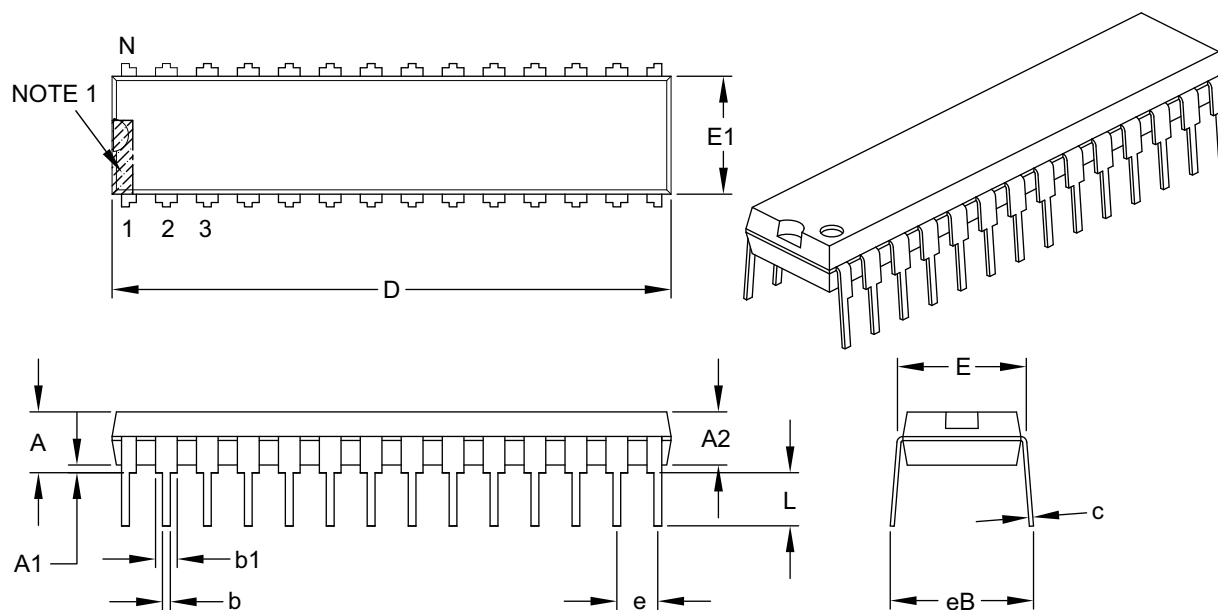
Note 1: These parameters are characterized, but not tested in manufacturing.

2: Because DMA transfers use the CPU data bus, this time is dependent on other functions on the bus.

33.2 Package Details

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	INCHES		
		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

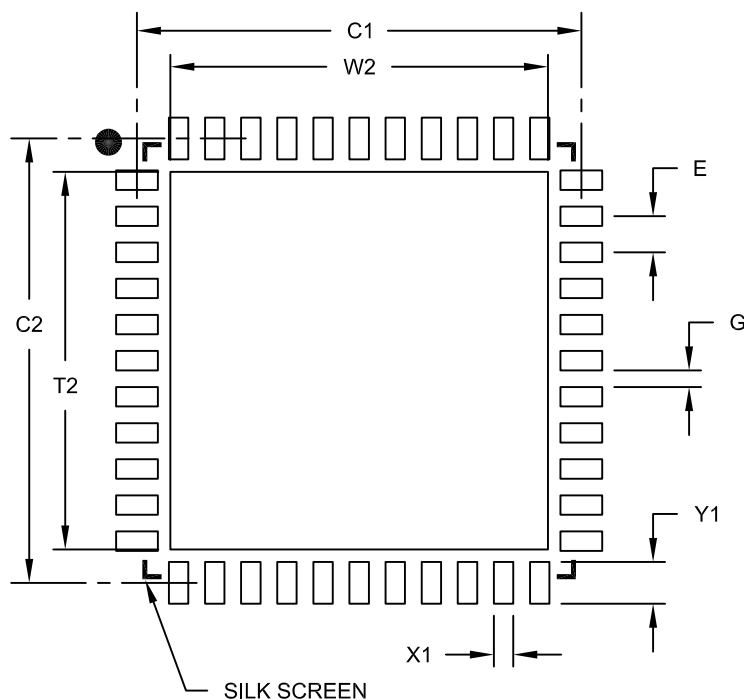
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- Dimensioning and tolerancing per ASME Y14.5M.
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W2			6.60
Optional Center Pad Length	T2			6.60
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103B

APPENDIX A: REVISION HISTORY

Revision A (April 2011)

This is the initial released version of the document.

Revision B (July 2011)

This revision includes minor typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in Table A-1.

TABLE A-1: MAJOR SECTION UPDATES

Section Name	Update Description
“High-Performance, 16-bit Digital Signal Controllers and Microcontrollers”	Changed all pin diagrams references of VLAP to TLA.
Section 4.0 “Memory Organization”	Updated the All Resets values for CLKDIV and PLLFBD in the System Control Register Map (see Table 4-35).
Section 5.0 “Flash Program Memory”	Updated “one word” to “two words” in the first paragraph of Section 5.2 “RTSP Operation” .
Section 9.0 “Oscillator Configuration”	Updated the PLL Block Diagram (see Figure 9-2). Updated the Oscillator Mode, Fast RC Oscillator (FRC) with divide-by-N and PLL (FRCPLL), by changing (FRCDIVN + PLL) to (FRCPLL). Changed (FRCDIVN + PLL) to (FRCPLL) for COSC<2:0> = 001 and NOSC<2:0> = 001 in the Oscillator Control Register (see Register 9-1). Changed the POR value from 0 to 1 for the DOZE<1:0> bits, from 1 to 0 for the FRCDIV<0> bit, and from 0 to 1 for the PLLPOST<0> bit; Updated the default definitions for the DOZE<2:0> and FRCDIV<2:0> bits and updated all bit definitions for the PLLPOST<1:0> bits in the Clock Divisor Register (see Register 9-2). Changed the POR value from 0 to 1 for the PLLDIV<5:4> bits and updated the default definitions for all PLLDIV<8:0> bits in the PLL Feedback Division Register (see Register 9-2).
Section 22.0 “Charge Time Measurement Unit (CTMU)”	Updated the bit definitions for the IRNG<1:0> bits in the CTMU Current Control Register (see Register 22-3).
Section 25.0 “Op amp/ Comparator Module”	Updated the voltage reference block diagrams (see Figure 25-1 and Figure 25-2).

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